Power and Power Management Issues

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The State of The Art



Blue Waters

~1 PF sustained >300,000 cores >1 PB of memory >10 PB of disk storage >500 PB of archival storage >100 Gbps connectivity



800 W



IH Server Node 8 MCM's (256 cores) 1 TB memory 8 TF (peak) Fully water cooled

Blue Waters Building Block 32 IH server nodes 32 TB memory 256 TF (peak) 4 Storage systems

4 Storage systems 10 Tape drive connections

10-20 MW

10MW = slightly over 10K American homes Nuclear Power Station in Clinton, IL=1,043MW

Power7 Chip

8 cores, 32 threads L1, L2, L3 cache (32 MB) Up to 256 GF (peak) 45 nm technology

Multi-chip Module

4 Power7 chips 128 GB memory 512 GB/s memory bandwidth 1 TF (peak)

Router 1,128 GB/s bandwidth

-acoma group

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Types of Power

- Dynamic power:
 - Related to switching activity of logic
 - Prop. to square of V_{dd} (cube)

$$P_{dyn} \propto CV_{dd}^2 f$$

- About 70% of all power
- Static (leakage) power:
 - Leakage of a transistor even if it does nothing
 - Exponential to T (also function of V_{dd})

$$P_{sta} \propto V_{dd} T^2 e^{-qV_t/kT}$$

- About 30% of all power



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Why Are Energy & Power an Issue?

- Ideal Scaling (or Dennard Scaling): Every semicond. generation:
 - Dimension: 0.7
 - Area of transistor: $0.7 \times 0.7 = 0.49$
 - Supply Voltage (V_{dd}), C: 0.7
 - Frequency: 1/0.7 = 1.4

$$P_{dyn} \propto CV_{dd}^2 f$$



- Real Scaling: V_{dd} does not decrease much.
 - If too close to threshold voltage (V_{th}) \rightarrow slow transistor
 - Switching speed is prop to (V_{dd} V_{th})

$$T_g \propto \frac{V_{dd}L_{eff}}{\mu(V_{dd} - V_t)^{\alpha}}$$

- Dynamic power density increases with smaller tech
- Additionally: There is the static power

Power density increases rapidly





What To Do?

- Evolutionary approaches
- Design computers for E & P efficiency from the ground up

Extreme Scale Computing





- Design circuits for E & P efficiency rather than speed
 - Low-swing on-chip interconnection network circuits
 - New memory layouts and bank organizations that minimize the capacitance switched per access
- Simplify the processor, shallow pipeline, less speculation
- Augment processing nodes with accelerators

Not enough





Designing Computers for E & P from the Ground Up

- New technologies:
 - Low supply voltage (V_{dd}) operation
 - Resistive memory
 - 3D die stacking
 - Efficient on-chip voltage conversion
 - Photonic interconnects
- New architectural designs:
 - Efficient support for high concurrency
 - Data transfer minimization





NTC Operation

- Advantages:
 - Reduces energy of an operation by 8-10x
 - Increases the delay by 10x
 - Hence: potentially reduces power consumption by 80-100x
- Drawbacks:
 - Lower speed (1/10)
 - Induces a 5x increase in gate delay variation
 - Potentially increases faults several orders of magnitude



